



- 1 Substrate: 3.18mm \pm 0.25mm [0.125" \pm 0.001"] FR4/G10 or equivalent high temp material. 17 μ m [1/2 oz.] Cu clad. Au plating. (RoHS)
- 2 Solder ball: Sn96.5Ag3.0Cu0.5

RoHS COMPLIANT

Description: BGA Surface Mount Adaptor
 Surface mount land pattern to solder balls. To be used with GHz sockets.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA456D-B-05F Drawing	Status: Released	Scale: 2:1	Rev: A
<p>© 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Suite 400 Burnsville MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: S.Natarajan		Date: 5/17/06
	File: SF-BGA456D-B-05F Dwg		Modified: